

FEATURES

- ❑ Avalanche Rugged Technology
- ❑ Rugged Gate Oxide Technology
- ❑ Lower Input Capacitance
- ❑ Improved Gate Charge
- ❑ Extended Safe Operating Area
- ❑ Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = -60V$
- ❑ Lower $R_{DS(ON)}$: 0.362 Ω (Typ.)

$BV_{DSS} = -60\text{ V}$

$R_{DS(on)} = 0.5\ \Omega$

$I_D = -1.8\text{ A}$

SOT-223



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	-60	V
I_D	Continuous Drain Current ($T_A=25^{\circ}\text{C}$)	-1.8	A
	Continuous Drain Current ($T_A=70^{\circ}\text{C}$)	-1.1	
I_{DM}	Drain Current-Pulsed ①	-14	A
V_{GS}	Gate-to-Source Voltage ②	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	110	mJ
I_{AR}	Avalanche Current ①	-1.8	A
E_{AR}	Repetitive Avalanche Energy ①	0.28	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-5.5	V/ns
P_D	Total Power Dissipation ($T_A=25^{\circ}\text{C}$) *	2.8	W
	Linear Derating Factor *	0.022	W/ $^{\circ}\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^{\circ}\text{C}$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient *	--	45	$^{\circ}\text{C/W}$

* When mounted on the minimum pad size recommended (PCB Mount).

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	-60	--	--	V	$V_{GS}=0V, I_D=-250\mu A$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	-0.05	--	$V/^\circ\text{C}$	$I_D=-250\mu A$ See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	--	-4.0	V	$V_{DS}=-5V, I_D=-250\mu A$
I_{GSS}	Gate-Source Leakage, Forward	--	--	-100	nA	$V_{GS}=-20V$
	Gate-Source Leakage, Reverse	--	--	100		$V_{GS}=20V$
I_{DSS}	Drain-to-Source Leakage Current	--	--	-10	μA	$V_{DS}=-60V$
		--	--	-100		$V_{DS}=-48V, T_C=125^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	0.5	Ω	$V_{GS}=-10V, I_D=-0.9A$ ④
g_{fs}	Forward Transconductance	--	1.43	--	S	$V_{DS}=-30V, I_D=-0.9A$ ④
C_{iss}	Input Capacitance	--	270	350	pF	$V_{GS}=0V, V_{DS}=-25V, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	90	135		
C_{rss}	Reverse Transfer Capacitance	--	25	35		
$t_{d(on)}$	Turn-On Delay Time	--	10	30	ns	$V_{DD}=-30V, I_D=-6.7A,$ $R_G=24\Omega$ See Fig 13 ④⑤
t_r	Rise Time	--	19	50		
$t_{d(off)}$	Turn-Off Delay Time	--	21	50		
t_f	Fall Time	--	16	40		
Q_g	Total Gate Charge	--	9	11	nC	$V_{DS}=-48V, V_{GS}=-10V,$ $I_D=-6.7A$ See Fig 6 & Fig 12 ④⑤
Q_{gs}	Gate-Source Charge	--	1.8	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	4.2	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	-1.8	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	-14		
V_{SD}	Diode Forward Voltage ④	--	--	-3.8	V	$T_J=25^\circ\text{C}, I_S=-1.8A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	--	75	--	ns	$T_J=25^\circ\text{C}, I_F=-6.7A$
Q_{rr}	Reverse Recovery Charge	--	0.17	--	μC	$di_F/dt=100A/\mu s$ ④

Notes ;

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② $L=40\text{mH}, I_{AS}=-1.8A, V_{DD}=-25V, R_G=27\Omega^*,$ Starting $T_J=25^\circ\text{C}$ ③ $I_{SD} \leq -6.7A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS},$ Starting $T_J=25^\circ\text{C}$ ④ Pulse Test : Pulse Width = $250\mu s,$ Duty Cycle $\leq 2\%$

⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

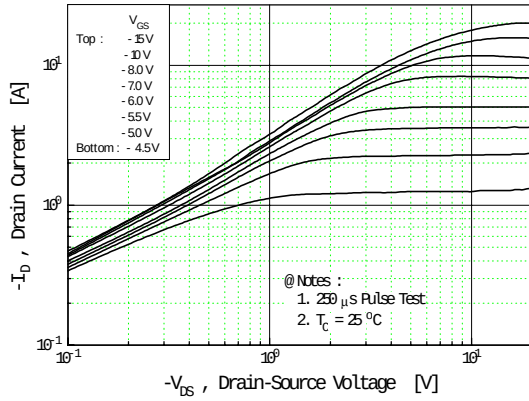


Fig 2. Transfer Characteristics

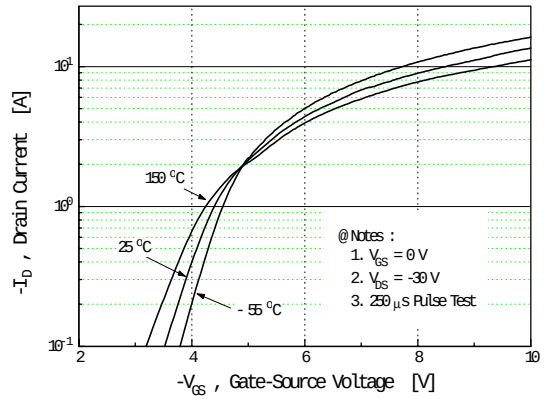


Fig 3. On-Resistance vs. Drain Current

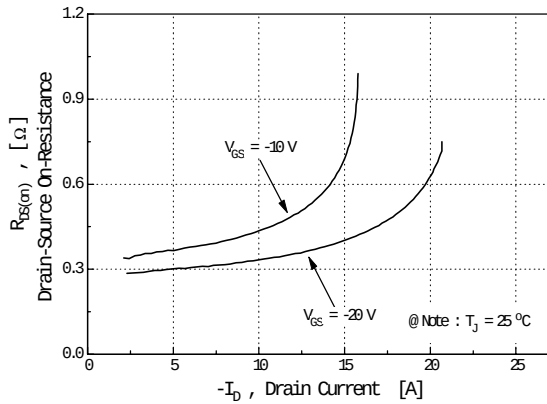


Fig 4. Source-Drain Diode Forward Voltage

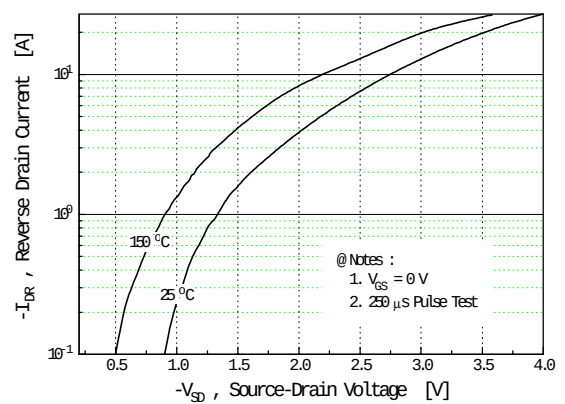


Fig 5. Capacitance vs. Drain-Source Voltage

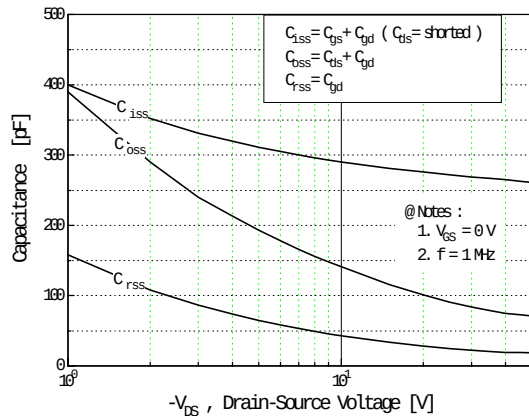


Fig 6. Gate Charge vs. Gate-Source Voltage

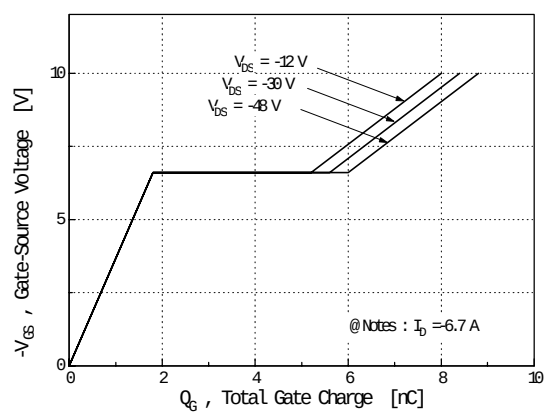


Fig 7. Breakdown Voltage vs. Temperature

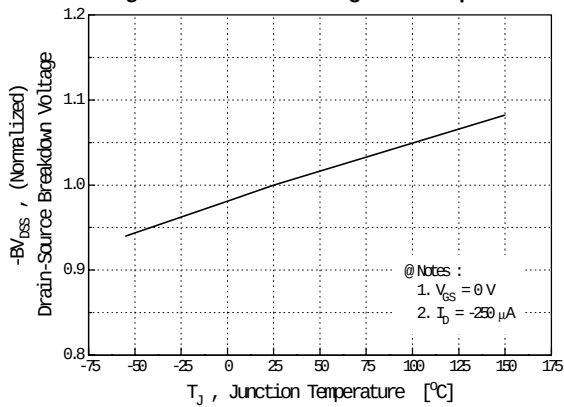


Fig 8. On-Resistance vs. Temperature

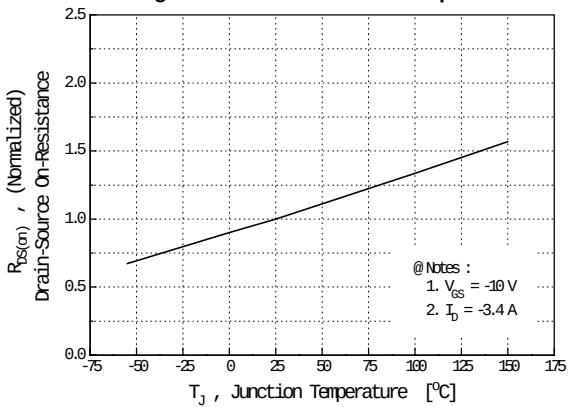


Fig 9. Max. Safe Operating Area

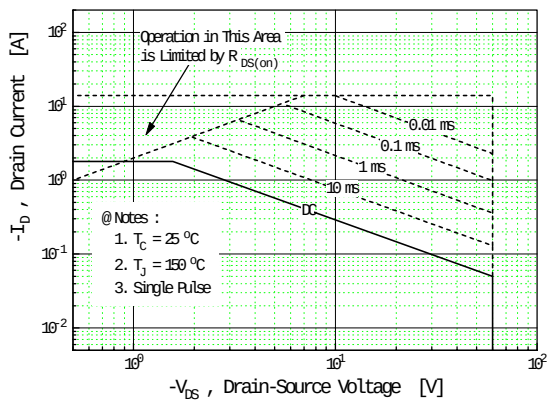


Fig 10. Max. Drain Current vs. Case Temperature

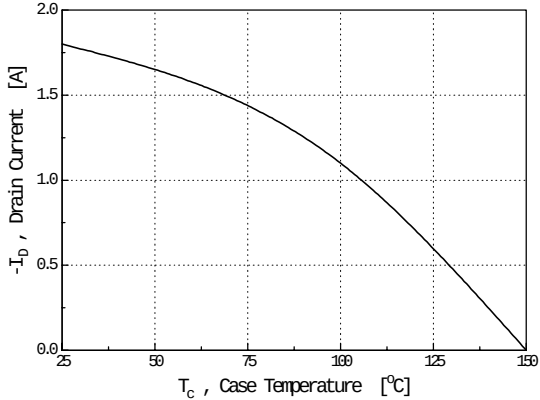


Fig 11. Thermal Response

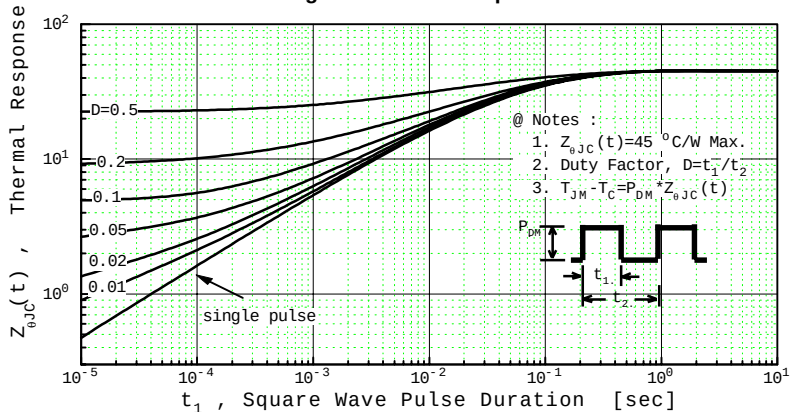


Fig 12. Gate Charge Test Circuit & Waveform

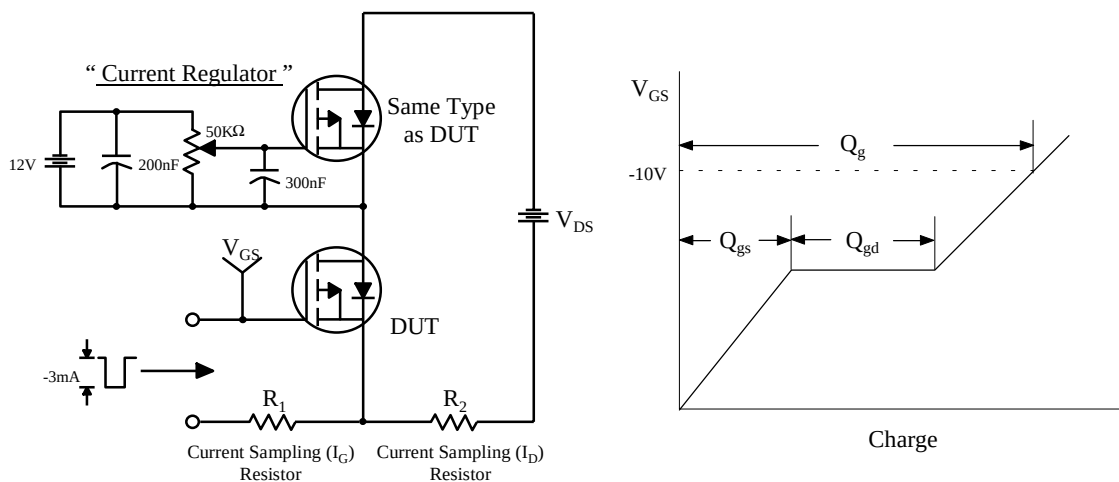


Fig 13. Resistive Switching Test Circuit & Waveforms

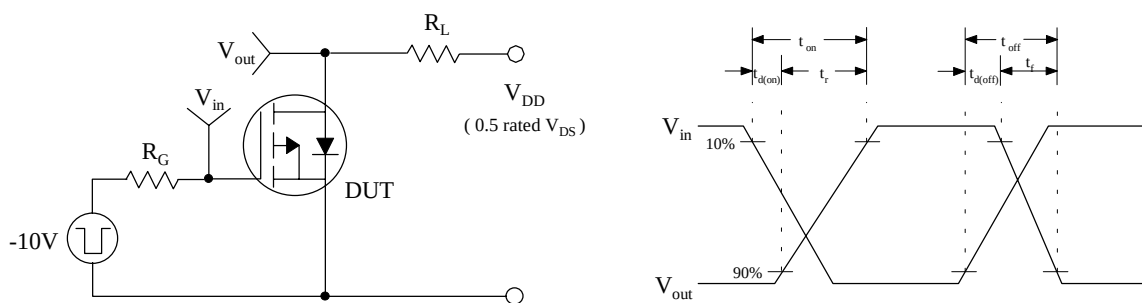


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

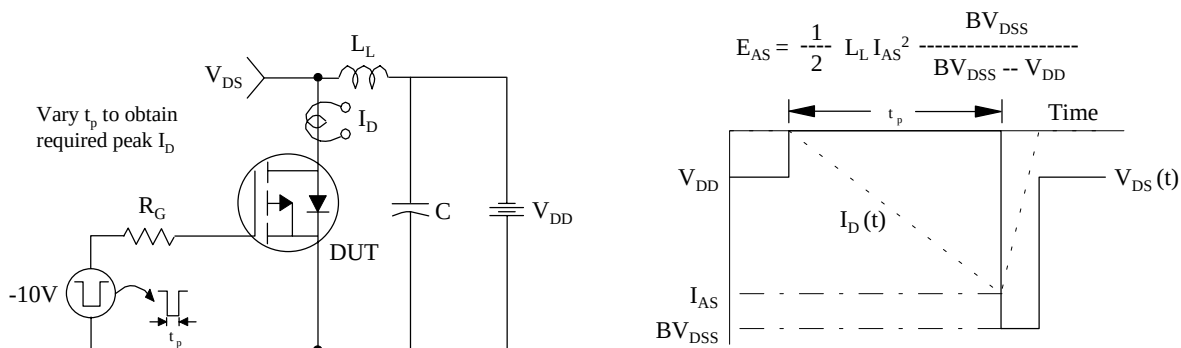
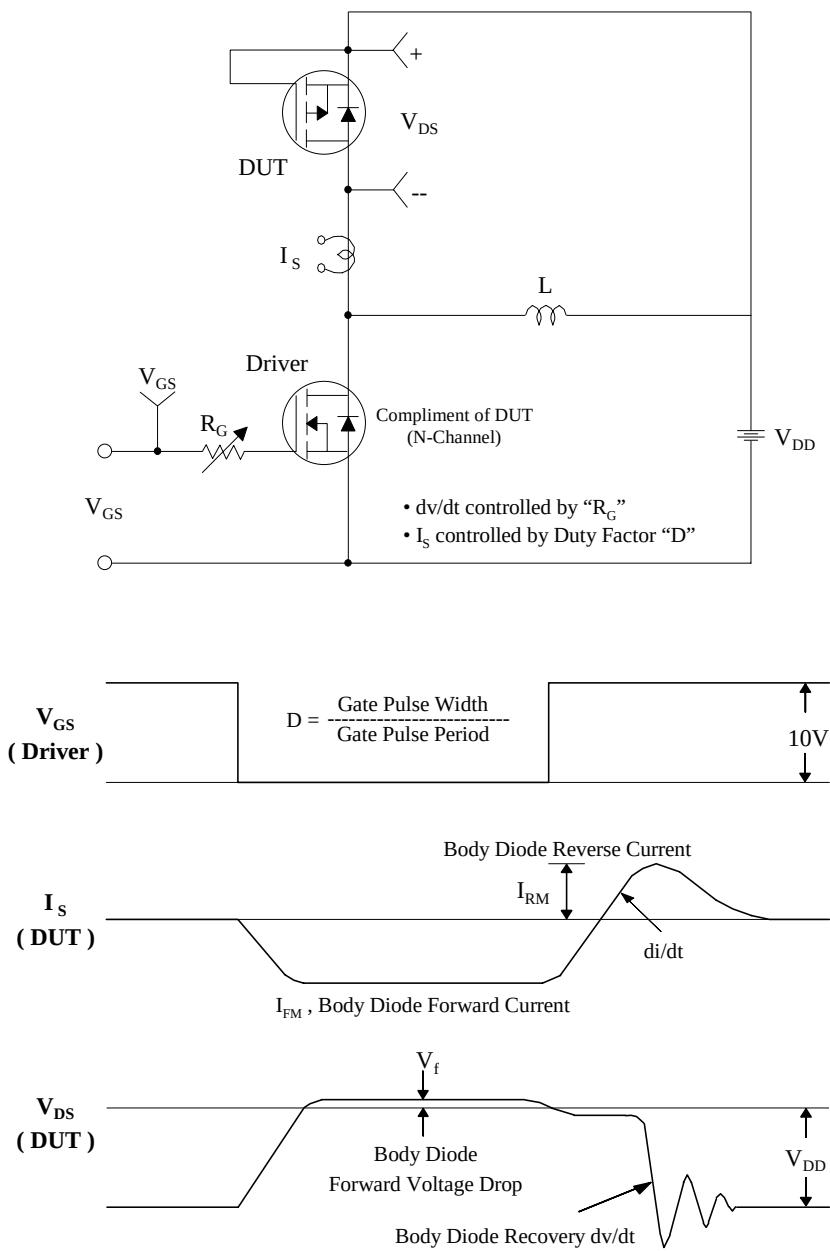


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE ^{Ex} TM	FACT TM	ImpliedDisconnect TM	PACMAN TM	SPM TM
ActiveArray TM	FACT Quiet Series TM	ISOPLANAR TM	POP TM	Stealth TM
Bottomless TM	FAST [®]	LittleFET TM	Power247 TM	SuperSOT TM -3
CoolFET TM	FAST ^r TM	MicroFET TM	PowerTrench [®]	SuperSOT TM -6
CROSSVOLT TM	FRFET TM	MicroPak TM	QFET TM	SuperSOT TM -8
DOME TM	GlobalOptoisolator TM	MICROWIRE TM	QS TM	SyncFET TM
EcoSPARK TM	GTO TM	MSX TM	QT Optoelectronics TM	TinyLogic TM
E ² CMOS TM	HiSeC TM	MSXPro TM	Quiet Series TM	TruTranslation TM
EnSigna TM	I ² C TM	OCX TM	RapidConfigure TM	UHC TM
Across the board. Around the world. TM		OCXPro TM	RapidConnect TM	UltraFET [®]
The Power Franchise TM		OPTOLOGIC [®]	SILENT SWITCHER [®]	VCX TM
Programmable Active Droop TM		OPTOPLANAR TM	SMART START TM	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.